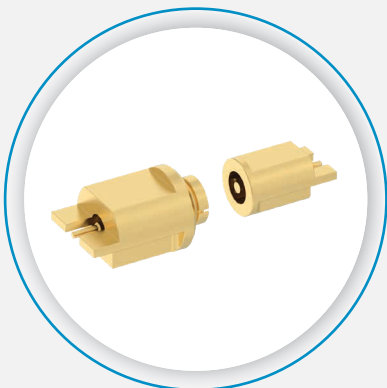
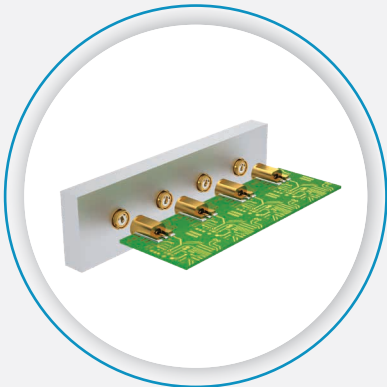
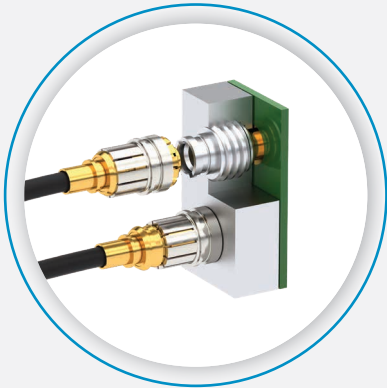


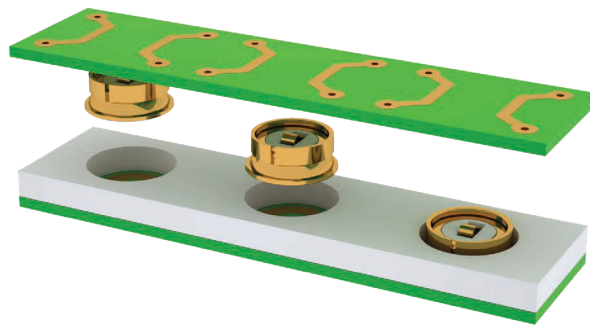
IMP FAMILY

The new generation of solderless interconnect solutions



Interconnect micro-miniature pressure contacts are the latest innovative solution for a variety of applications, including radar. Their solderless system meets the new integration needs of Board-to-Board solutions.

The introduction of new antennas and radar for land, naval and air applications, including fighter jets, missiles and UAVs, is bringing new requirements to the market to achieve the highest performance levels. Radiall has introduced innovative connectors to follow the trend of miniaturization of applications while increasing performance. The products provide increased integration density, lighter interconnection and simplified product structure.



Example of IMP-LP

The IMP solderless series provides a total cost savings by eliminating the constraint related to soldering during installation, life cycle and maintenance.



IMP-HD
Low Phase Noise option available



IMP-Low Profile
Simple version



IMP-Low Profile
Double version

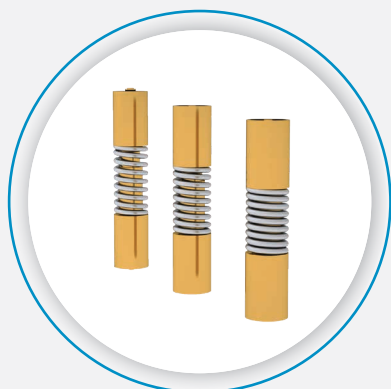


IMP-Low Profile Hybrid
Available with SMP, SMP-Lock, SMPM, SMPM-Lock, SBMA and MCC#12 interface



IMP-Nano
Available in several configurations

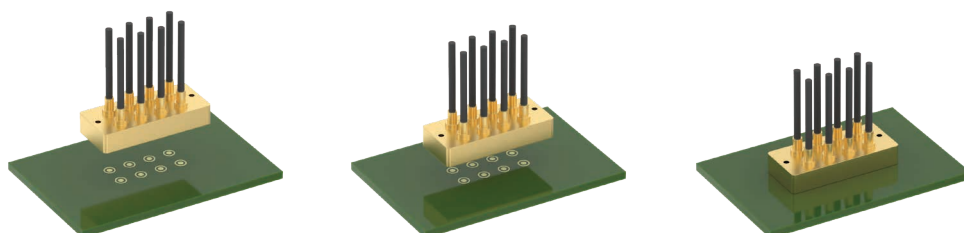
Radiall's IMP product line offers a wide range of standard and custom connectors to address all customer requests.



Radiall designs IMP connectors with advanced features to meet the most demanding performance requirements.

With its Board-to-Board interconnect innovations, Radiall reduces the interference typical with conventional solutions that can affect signal performance. IMP connectors feature a simplified structure that divides the insertion loss by three (≤ 0.25 dB). They can be used in applications that require high crosstalk performance.

The use of solderless technology improves the reliability of interconnection by limiting the gold removal process before soldering, as gold inside the solder could generate cracks during thermal cycling.



Example of an Assembly with IMP Hybrid

FEATURES & BENEFITS

- Up to 65 GHz
- Low phase noise: -20 to -30 dB @ 1 kHz
- Insertion loss: ≤ 0.25 dB
- Crosstalk: -85 dB typ. @ 18 GHz
- Low pitch: $\varnothing 2.45$ mm
- Board-to-Board distance: 1.41 mm to 16.5 mm

APPLICATIONS

- Active antennas and radar applications
- Board-to-Board, board-to-module and board-to-panel interconnections